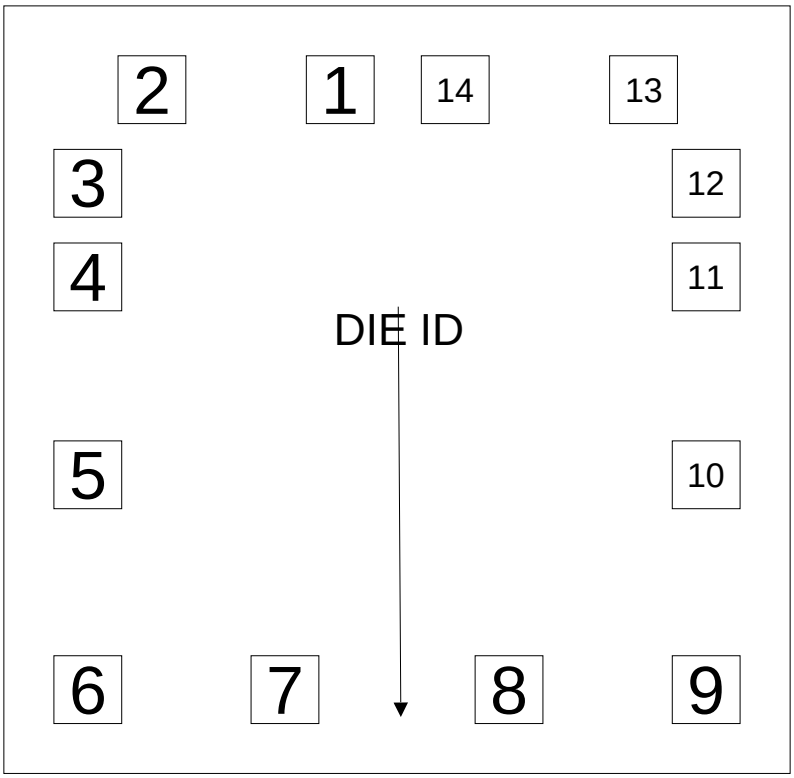
LM139 MDE MCD2610A
SMD#5962R9673802V9A
LOW POWER LOW OFFSET VOLTAGE QUAD COMPARATOR

NOV 18, 2008

DIE LAYOUT (H-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM1901H	Bond Pad Opening Size (min)	92.00µm x 92.00µm
Die Step	H	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM ONLY
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1066.8µm x 1041.4µm 42.0mils x 41.0mils	Back Side Connection	Floating or GND
Thickness	330µm Nominal		
Min Pitch	127µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(H-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
Output 2	1	-77	407	92	x	92
Output 1	2	-333	407	92	x	92
V+	3	-420	280	92	x	92
- Input 1	4	-420	153	92	x	92
+ Input 1	5	-420	-116	92	x	92
- Input 2	6	-420	-407	92	x	92
+ Input 2	7	-152	-407	92	x	92
- Input 3	8	152	-407	92	x	92
+ Input 3	9	420	-407	92	x	92
- Input 4	10	420	-116	92	x	92
+ Input 4	11	420	153	92	x	92
Gnd	12	420	280	92	x	92
Output 4	13	335	407	92	x	92
Output 3	14	79	407	92	x	92

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Notes

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